

## GP80001C IST COUPON DESIGN INFORMATION (Back-Plane)

(With capacitance holes)

This package contains a design file for a generic Interconnect Stress Test (IST) Test Coupon containing **Plated Through Hole** Technology, on a 5.0" (126.9 mm) X 0.8" (20.3 mm) coupon with a total thickness greater than .125" (3.2mm) for Back-Plane style PWB's with a minimum of 10 layers. This coupon is designed with a .080" (2mm) connector style grid. The maximum-drilled hole for the Power and Sense circuits is .056" (1.42mm) and pad size is .068" (1.73mm). Decreasing these feature sizes will not affect the coupon functionality, but increasing these feature sizes may result in shorts or excessively small clearances. Instructions on how to create a custom IST coupon for a specific product are included.

Note: If this generic design is not suitable to construct a coupon consistent with the actual product, custom coupon design services are available from PWB.

